

In the Claims:

This listing of claims replaces all prior versions and listings of claims for this application.

1. (Currently amended) A socket or adapter~~[[-]]~~device adapted for carrying a semiconductor device to be tested, the ~~[[test]]~~ socket or adapter device comprising ~~at least one a~~ plurality of connection ~~[[pin]]~~ pins, wherein the connection pins extend ~~pin extends~~ from a lower surface of the socket or adapter device in a downward direction, the connection pins ~~[[pin]]~~ being configured to be connected to a corresponding contact device by solderless surface mounting, and the end ~~sections~~ section of the connection pins have ~~pin has~~ a shape bent back in an upward direction, the ~~bent back end section of the connection pin electrically contacts an electrical contact of the contact device~~ end sections of the connection pins viewed from the bottom of the socket or adapter being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device.

2. (Original) The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that it can be loaded with a corresponding semiconductor device.

3. (Original) The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is configured for performing a burn-in test and can be loaded with a corresponding semiconductor device.

4. (Currently amended) The socket or adapter device according to claim 1, wherein the connection ~~pin is~~ pins are made of a flexible or resilient material.

5. (Original) The socket or adapter device according to claim 4, wherein the metal alloy includes copper and/or beryllium.

6. (Currently amended) The socket or adapter device according to claim 1, wherein at least one section of the connection ~~[[pin]]~~ pins has an arcuate or bent shape.

7. (Original) The socket or adapter device according to claim 1, wherein the device comprising the contact device is a circuit board configured to be connected to a testing apparatus.

8. (Original) The socket or adapter device according to claim 1, wherein the device comprising the contact device is a testing apparatus.

9. (Currently amended) A system, comprising:
at least one socket or adapter device; and
at least one semiconductor device testing apparatus or at least one circuit board, wherein

the socket or adapter device comprises a plurality of ~~at least one~~ connection ~~[[pin]]~~ pins which ~~[[is]]~~ are configured to be connected to a corresponding contact device for connection to the testing apparatus or to the circuit board that can be connected with a testing apparatus, and

wherein the connection ~~pin extends~~ pins extend from a lower surface of the socket or adapter device in a downward direction, the end ~~section~~ sections of the connection ~~pin has~~ pins have a shape bent back in an upward direction, ~~the bent back end section of the connection pin electrically contacts an electrical contact of the contact device~~ the end sections of the connection pins viewed from the bottom of the socket or adapter being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device, and the connection ~~pin~~ pins are connected to the contact device by surface mounting.

10. (Currently amended) The system according to claim 9, wherein the connection ~~pin is~~ pins are connected to the contact device without soldering.

11. (Currently amended) The system according to claim 9, wherein a device is provided such that the connection ~~pin is~~ pins are pressed against the contact device.

12. (Original) The system according to claim 11, wherein the device is an appropriate screw connection.

13. (Original) The system according to claim 11, wherein the device is an appropriate clamping connection.

14. (Original) The system according to claim 10, wherein the socket or adapter device comprises a plurality of connection pins, each being connected to corresponding contact ~~devices~~ device, and wherein the conneciton pins each are connected to the respectively corresponding contact devices without soldering.

15. (Currently amended) A method for testing semiconductor devices, comprising:

connecting a socket or adapter device to a testing system, wherein a plurality of at least one connection pin is pins are connected to a corresponding contact device;

loading the socket or adapter device with a semiconductor device to be tested, wherein

the connection pins extend ~~pin extends~~ from a lower surface of the socket or adapter device in a downward direction, the end ~~section~~ sections of the connection pins have a shape bent back in an upward direction, ~~the bent back end section of the connection pin electrically contacts an electrical contact of the contact device~~ the end sections of the connection pins viewed from the bottom of the socket or adapter

being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device, and the connection of the connection ~~[[pin]] pins~~ too the contact device are ~~is performed~~ by solderless surface mounting.